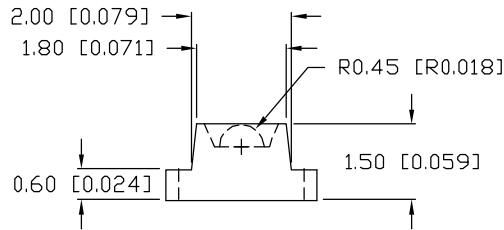
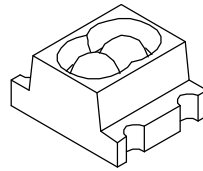
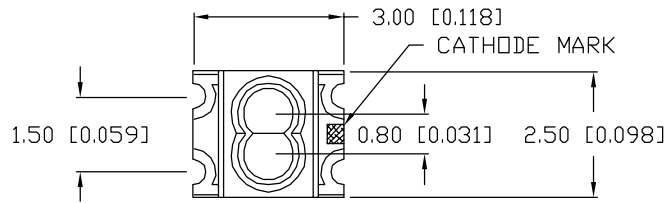


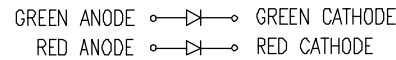
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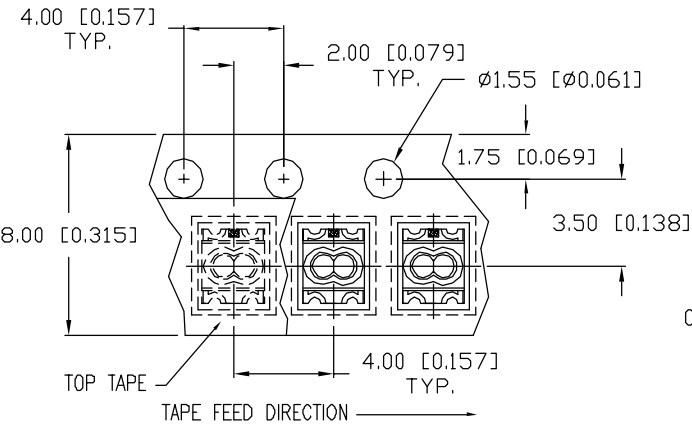
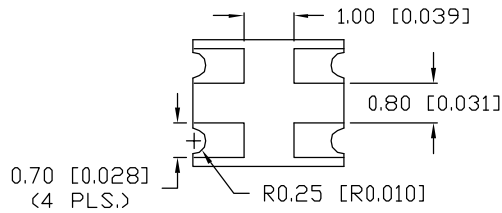
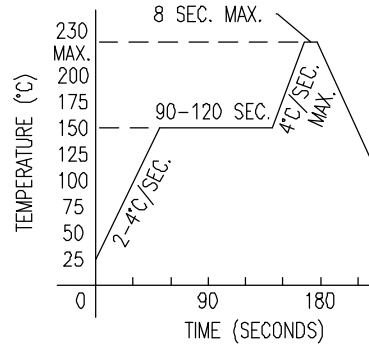
REV.  
B



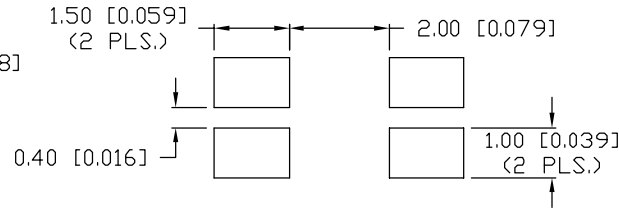
TOP VIEW POLARITY



REFLOW PROFILE



RECOMMENDED SOLDER PAD LAYOUT



NOTES:

1. THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$				
PARAMETER	MIN	TYP	MAX	UNITS TEST COND
PEAK WAVELENGTH		660 (RED)		nm
		565 (GREEN)		nm
FORWARD VOLTAGE (R/G)		1.7/2.2	2.2/2.6	$V_f$
REVERSE VOLTAGE	5.0			$V_r$ $I_r=100\mu\text{A}$
AXIAL INTENSITY (R/G)		35/30		mcd $I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta
EMITTED COLOR: RED/GREEN				
EPOXY LENS FINISH: WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C			
PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT	(R/G)	25/30	mA
POWER DISSIPATION		100	mW
DERATE FROM 25°C		-1.0	mW/°C
OPERATING TEMP.		-40 TO +85	°C
STORAGE TEMP.		-40 TO +90	°C

\*  $t < 10\mu\text{s}$

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION MAX.= +0.00 -DECIMAL PRECISION

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REV.  
B

PART NUMBER  
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2.7mm x 3.0mm PCB, SURFACE MOUNT LED,  
SUPER RED/SUPER GREEN CHIPS,  
WATER CLEAR LENS, TAPE AND REEL.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 11.6.00
			PAGE: 1 OF 1
			SCALE: N/A